



## Product Change Notification / JAON-29UXDQ760

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### Date:

06-Jun-2016

### Product Category:

16-Bit - Microcontrollers and Digital Signal Controllers, 32-bit Microcontrollers, 8-bit Microcontrollers, Capacitive Touch Sensors

### PCN Type:

Manufacturing Change

### Notification Subject:

CCB 1751 and 1751.01 Cancellation Notice: For the qualification of CuPdAu bond wire in selected products of the 0.18um TSMC CUP wafer technology available in 64L and 44L TQFP (10x10mm) package at MTAI

### Notification Text:

**PCN Status:** Cancellation notification

**Microchip Parts Affected:** This change would have affected selected products of the 0.18um TSMC CUP wafer technology available in 64L and 44L TQFP (10x10mm) package at MTAI assembly site.

**Description of Change:** This qualification was originally performed to qualify palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 0.18um TSMC CUP wafer technology available in 64L and 44L TQFP (10x10mm) package at MTAI assembly site.

**Impacts to Data Sheet:** Not Applicable

**Reason for Change:** Microchip has decided not to qualify palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 0.18um TSMC CUP wafer technology available in 64L and 44L TQFP (10x10mm) package at MTAI assembly site.

**Change Implementation Status:** Not Applicable

**Estimated First Ship Date:** Not Applicable

**Markings to Distinguish Revised from Unrevised Devices:** Not Applicable

**Revision History:**

**October 14, 2015:** Issued initial notification.

**January 21, 2016:** Revised the estimated first ship date from November 30, 2015 to April 20, 2016. **June 6, 2016:** Issued cancellation notice for the proposed qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 0.18um TSMC CUP wafer technology available in 64L and 44L TQFP (10x10mm) package at MTAI assembly site.

**Attachments:**

[PCN\\_JAON-29UXDQ760\\_Affected\\_CPN.pdf](#)

[PCN\\_JAON-29UXDQ760\\_Affected\\_CPN.xls](#)

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